

App. No. 10/085,552  
Amendment dated September 20 2004  
Reply to Office action of August 18, 2004

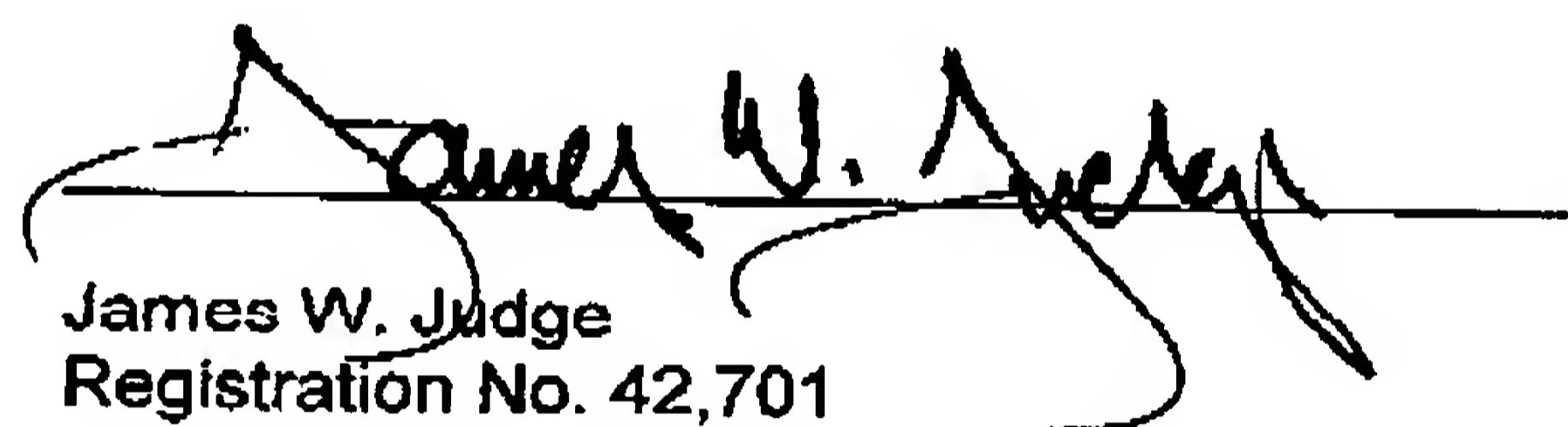
claimed in claims 8-13. Namely the Office action has not expressly set forth how such a substitution would produce—to quote the recitation common to claims 8-13—"A compound semiconductor wafer including an In-containing-compound semiconductor surface layer, . . . [the] carrier concentration in the wafer [being] non-invasively profiled" so that the wafer "can be employed as it is for device processing."

Accordingly, for the foregoing reasons it is respectfully submitted that claims 8-13 are drawn to a product inseparably distinct from the process of making that product, and as such should be examined on the merits together with the claims drawn to the process in the present application.

Favorable action by the Examiner at an early date is solicited.

Respectfully submitted,

September 20, 2004



James W. Judge  
Registration No. 42,701

JUDGE PATENT FIRM  
Rivière Shukugawa 3<sup>rd</sup> Fl.  
3-1 Wakamatsu-cho  
Nishinomiya-shi, Hyogo 662-0035  
JAPAN

Telephone: 305-938-7119  
Voicemail/Fax: 703-997-4565  
e-mail: jj@judgepat.jp